

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	TAKASHI MATSUDA	10/12/2018
	MASAFUMI IWAKI	10/12/2018
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	TAIYO YUDEN CO., LTD.	
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<b>State/Country:</b>	JAPAN	
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<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	16175235
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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<b>ATTORNEY DOCKET NUMBER:</b>	0855.1005	
<b>NAME OF SUBMITTER:</b>	MICHAEL D.STEIN	
<b>SIGNATURE:</b>	/Michael D. Stein/	
<b>DATE SIGNED:</b>	10/31/2018	
<b>Total Attachments: 1</b>		
source=09890US_Combined Declaration-Assignment#page1.tif		

**COMBINED DECLARATION/ASSIGNMENT FOR UTILITY/DESIGN PATENT APPLICATION****OATH OR DECLARATION**

As a below named inventor, I hereby declare that:

This combined declaration and assignment is directed to the application entitled:

**ACOUSTIC WAVE RESONATOR, FILTER, AND MULTIPLEXER**

the specification of which is attached hereto, or was filed on \_\_\_\_\_ as United States Application Number (or PCT International Application Number) \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

Any registered attorney of STEIN IP, LLC, 1990 M St., N.W., Suite 610, Washington, D.C. 20036 (202-216-9505), USPTO Customer Number 49,455, is hereby authorized to insert the specified data into the above paragraph, when known.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

**ASSIGNMENT**

IN CONSIDERATION of good and valuable consideration paid to me, an undersigned inventor, by

**Taiyo Yuden Co., Ltd.**  
7-19 Kyobashi 2-chome, Chuo-ku, Tokyo, 104-0031, Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, I hereby sell, assign and transfer to ASSIGNEE the entire and exclusive right, title and interest to the above-identified application and the claimed invention therein, and any continuation, division, renewal, substitute, reissue or reexamination application based thereon (collectively, hereinafter, "said application(s)"), and all Letters Patent of the United States granted on said application(s), for the full term or terms for which the said Letters Patent may be granted and including any extensions thereof (collectively, hereinafter, "said Letters Patent").

I agree, when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent, in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

I covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

IN WITNESS WHEREOF, I have affixed my signature on the date beneath.

Full name of sole/first inventor Takashi MATSUDA

Inventor's Signature Takashi Matsuda Date Executed Oct. 12, 2018

Inventor's Mailing Address c/o TAIYO YUDEN CO., LTD., 7-19 Kyobashi 2-chome, Chuo-ku, Tokyo, 104-0031, Japan

Inventor's Residence Tokyo, JAPAN

Full name of second inventor Masafumi IWAKI

Inventor's Signature Masafumi Iwaki Date Executed Oct. 12, 2018

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